Unit: mm

#### **TOSHIBA Photocoupler Photorelay**

## **TLP3100**

## Measurement Equipment FA (Factory Automation) Power Line Control

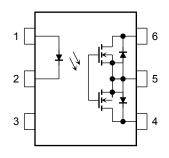
The Toshiba TLP3100 consists of an aluminum gallium arsenide infrared emitting diode optically coupled to a photo-MOSFET in a SOP, which is suitable for surface-mount assembly. The TLP3100 features high ON-state current and low ON-state resistance, hence the TLP3100 is suitable to control a power line.

- 6-pin SOP (2.54SOP6): 2.1 mm high, 2.54 mm pitch
- Normally opened (form A) device
- Peak OFF-state voltage: 20 V (min)
- Trigger LED current: 3 mA (max)
- ON-state current: 2.5 A (max) (Ta=50°C)
- ON-state resistance:  $0.02 \Omega$  (typ.),  $0.05 \Omega$  (max)
- Capacitance between output terminals: 1000 pF (typ.)
- OFF-state current: 10 nA (max)
- Isolation voltage: 1500 V<sub>rms</sub> (min)
- UL approved: UL1577, File No.E67349
- cUL approved :CSA Component Acceptance Service
   No. 5A, File No.E67349

# 6.3±0.25 1 2 3 6.3±0.25 1 0.6±0.3 TOSHIBA 11-7C1

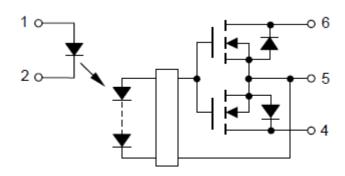
Weight: 0.13 g (typ.)

#### Pin Configuration (top view)



- 1: Anode
- 2: Cathode
- 3: N.C.
- 4: Drain D1
- 5: Source
- 6: Drain D2

#### **Schematic**



Start of commercial production 2008-04

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit	
	Forward curi	rent	lF	30	mA	
	Forward curi	rent derating (Ta ≥ 25°C)	ΔI <sub>F</sub> /°C	-0.3	mA/°C	
150	Reverse volt	age	V <sub>R</sub>	5	V	
LED	Diode power	dissipation	P <sub>D</sub>	50	mW	
	Diode power	dissipation derating (Ta ≥ 25°C)	ΔP <sub>D</sub> /°C	-0.5	mW/°C	
	Junction tem	perature	Tj	125	°C	
	Off-state out	put terminal voltage	V <sub>OFF</sub>	20	V	
	On-state current	A connection		2.5		
		B connection	I <sub>ON</sub>	2.5	Α	
		C connection		5.0		
	On-state current derating (Ta ≥ 50°C)	A connection		-33.3		
Detector		B connection	ΔI <sub>ON</sub> /°C	-33.3	mA/°C	
		C connection		-66.7		
	Output power	er dissipation	PO	364.5	mW	
	Output power	er dissipation derating (Ta ≥ 50°C)	ΔP <sub>O</sub> /°C	-4.86	mW / °C	
	Junction tem	perature	Tj	125	°C	
Storage temperature			T <sub>stg</sub>	−55 to 125	°C	
Operating temperature			T <sub>opr</sub>	−40 to 85	°C	
Lead soldering temperature (10 s)			T <sub>sol</sub>	260	°C	
Isolation (AC, 1 mi	voltage nute, R.H. ≤ 6	(Note 1)	BVS	1500	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Note 1: Device considered a two-terminal device: Pins 1 and 2 shorted together, and pins 3 and 4 shorted together.

#### Caution

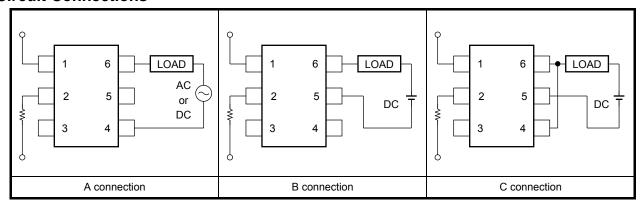
This device is sensitive to electrostatic discharge. When using this device, please ensure that all tools and equipment are earthed.

#### **Recommended Operating Conditions**

Characteristics	Symbol	Min	Тур.	Max	Unit
Supply voltage	$V_{DD}$	_	_	20	V
Forward current	ΙF	5	10	20	mA
Operating temperature	T <sub>opr</sub>	-20	_	65	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

#### **Circuit Connections**



#### **Individual Electrical Characteristics (Ta = 25°C)**

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
	Forward current	V <sub>F</sub>	I <sub>F</sub> = 10 mA	1.18	1.33	1.48	V
LED	Reverse current	I <sub>R</sub>	V <sub>R</sub> = 5 V	_	_	10	μА
	Capacitance between terminals	C <sub>T</sub>	V <sub>F</sub> = 0 V, f = 1 MHz	_	70	_	pF
ctor	OFF-state current	I <sub>OFF</sub>	V <sub>OFF</sub> = 20 V	_	_	10	nA
Detector	Capacitance between terminals	C <sub>OFF</sub>	V = 0 V, f = 1 MHz	ı	1000	_	pF

#### **Coupled Electrical Characteristics (Ta = 25°C)**

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Trigger LED current		I <sub>FT</sub>	I <sub>ON</sub> = 100 mA	_	_	3	mA
Return LED current		I <sub>FC</sub>	I <sub>OFF</sub> = 10 μA	0.1	_	_	mA
On-state resistance	A connection		I <sub>ON</sub> = 2.0 A, I <sub>F</sub> = 5 mA, t<1s	_	0.02	0.05	
	B connection	R <sub>ON</sub>	I <sub>ON</sub> = 2.0 A, I <sub>F</sub> = 5 mA, t<1s	_	0.01	0.025	Ω
	C connection		I <sub>ON</sub> = 4.0 A, I <sub>F</sub> = 5 mA, t<1s	—	0.005	_	

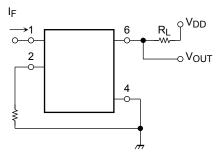
#### **Isolation Characteristics (Ta = 25°C)**

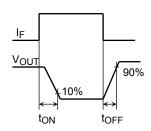
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Capacitance input to output	Cs	V <sub>S</sub> = 0 V, f = 1 MHz	_	8.0	_	pF
Isolation resistance	R <sub>S</sub>	V <sub>S</sub> = 500 V, R.H. ≤ 60%	5 × 10 <sup>10</sup>	10 <sup>14</sup>	_	Ω
		AC, 1 minute	1500	_	_	\/rma
Isolation voltage	BVS	AC, 1 second (in oil)	_	3000	_	Vrms
		DC, 1 minute (in oil)	_	3000	_	Vdc

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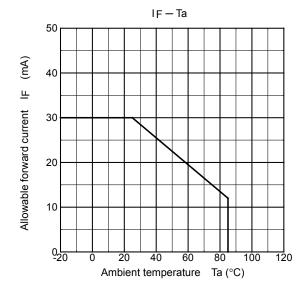
### **Switching Characteristics (Ta = 25°C)**

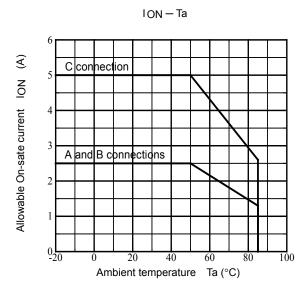
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Turn-ON time	t <sub>ON</sub>	$R_L = 200 \Omega$	_	1.5	5.0	mo
Turn-OFF time	toff	$V_{DD} = 10 \text{ V}, I_F = 5 \text{ mA}$ (Note 2)	_	0.1	1.0	ms

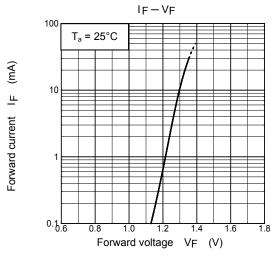


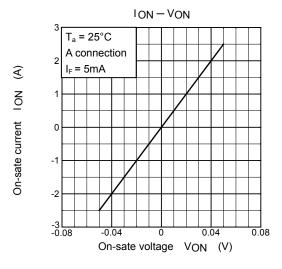


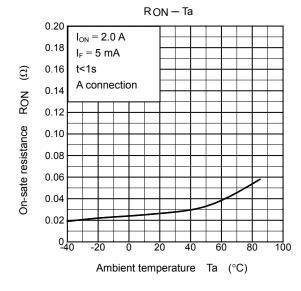
Note 2: Switching time test circuit

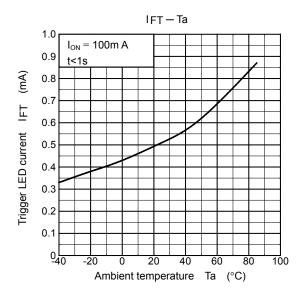






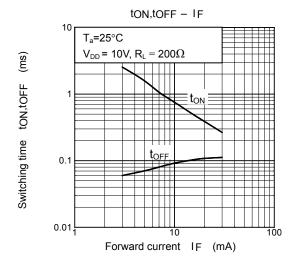


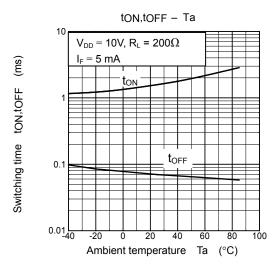


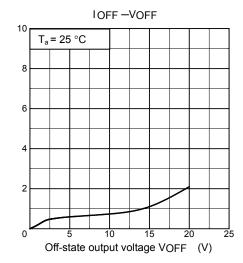


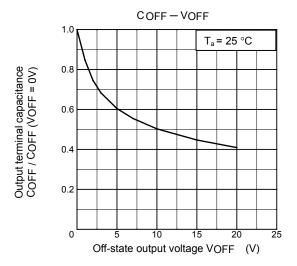
(nA)

Off-state current IOFF









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